

BC372, BC373

High Voltage Darlington Transistors

NPN Silicon

Features

- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage BC372 BC373	V_{CEO}	100 80	Vdc
Collector – Base Voltage BC372 BC373	V_{CES}	100 80	Vdc
Emitter – Base Voltage	V_{EBO}	12	Vdc
Collector Current – Continuous	I_C	1.0	Adc
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $T_A = 25^\circ\text{C}$	P_D	625 5.0	mW mW/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $T_A = 25^\circ\text{C}$	P_D	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C/W}$

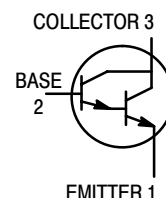
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

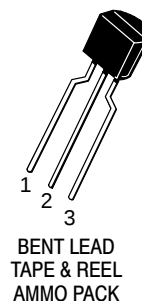
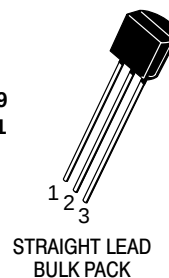


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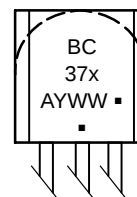
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TO-92
CASE 29
STYLE 1



MARKING DIAGRAM



x = 2 or 3
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BC372G	TO-92 (Pb-Free)	5000 Units / Bulk
BC373RL1	TO-92	2000 / Tape & Reel
BC373RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BC372, BC373

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector – Emitter Breakdown Voltage ⁽¹⁾ ($I_C = 100\ \mu\text{Adc}$, $I_E = 0$)	BC372 BC373	$V_{(BR)CES}$	100 80	– –	– –	Vdc
Collector – Base Breakdown Voltage ($I_C = 100\ \mu\text{Adc}$, $I_E = 0$)	BC372 BC373	$V_{(BR)CBO}$	100 80	– –	– –	Vdc
Emitter – Base Breakdown Voltage ($I_E = 10\ \mu\text{Adc}$, $I_C = 0$)		$V_{(BR)EBO}$	12	–	–	Vdc
Collector Cutoff Current ($V_{CB} = 80\ \text{Vdc}$, $I_E = 0$) ($V_{CB} = 60\ \text{Vdc}$, $I_E = 0$)	BC372 BC373	I_{CBO}	– –	– –	100 100	nAdc
Emitter Cutoff Current ($V_{EB} = 10\ \text{V}$, $I_C = 0$)		I_{EBO}	–	–	100	nAdc

ON CHARACTERISTICS (Note 1)

DC Current Gain ($I_C = 250\ \text{mAdc}$, $V_{CE} = 5.0\ \text{Vdc}$) ($I_C = 100\ \text{mAdc}$, $V_{CE} = 5.0\ \text{Vdc}$)		h_{FE}	8.0 10	– –	– 160	K
Collector – Emitter Saturation Voltage ($I_C = 250\ \text{mAdc}$, $I_B = 0.25\ \text{mAdc}$)		$V_{CE(sat)}$	–	1.0	1.1	Vdc
Base – Emitter Saturation Voltage ($I_C = 250\ \text{mAdc}$, $I_B = 0.25\ \text{mAdc}$)		$V_{BE(sat)}$	–	1.4	2.0	Vdc

DYNAMIC CHARACTERISTICS

Current–Gain Bandwidth Product ($I_C = 100\ \text{mAdc}$, $V_{CE} = 5.0\ \text{Vdc}$, $f = 100\ \text{MHz}$)		f_T	100	200	–	MHz
Output Capacitance ($V_{CB} = 10\ \text{Vdc}$, $I_E = 0$, $f = 1.0\ \text{MHz}$)		C_{ob}	–	10	25	pF
Noise Figure ($I_C = 1.0\ \text{mAdc}$, $V_{CE} = 5.0\ \text{Vdc}$, $R_g = 100\ \text{k}\Omega$, $f = 1.0\ \text{kHz}$)		NF	–	2.0	–	dB

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle 2.0%.

BC372, BC373

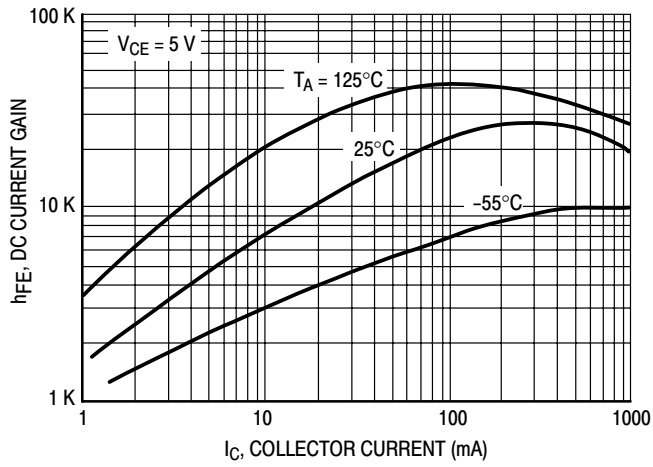


Figure 1. DC Current Gain

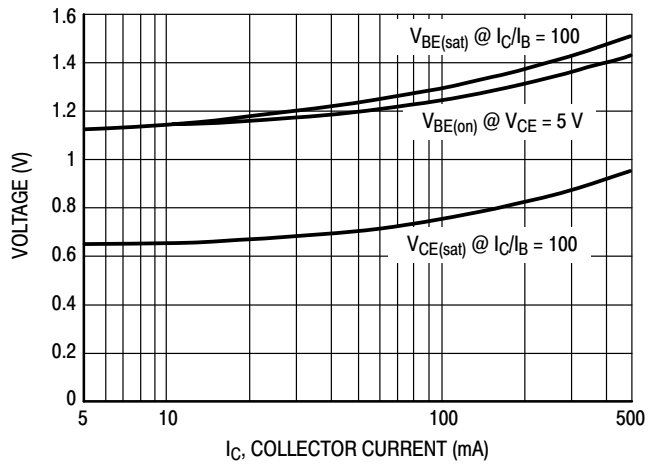


Figure 2. "Saturation" and "On" Voltages

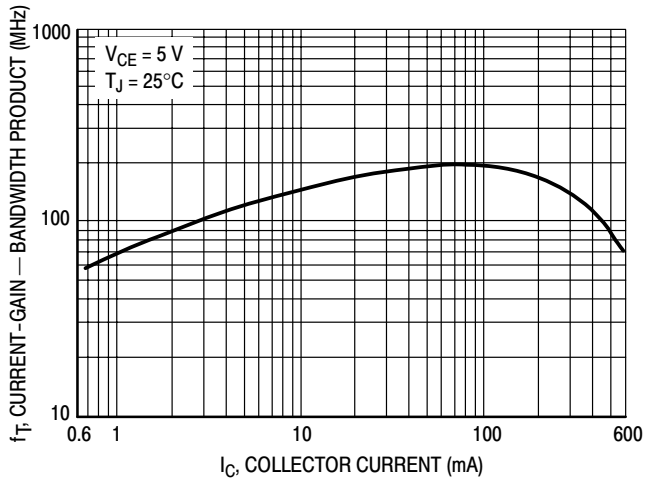


Figure 3. Current-Gain — Bandwidth Product

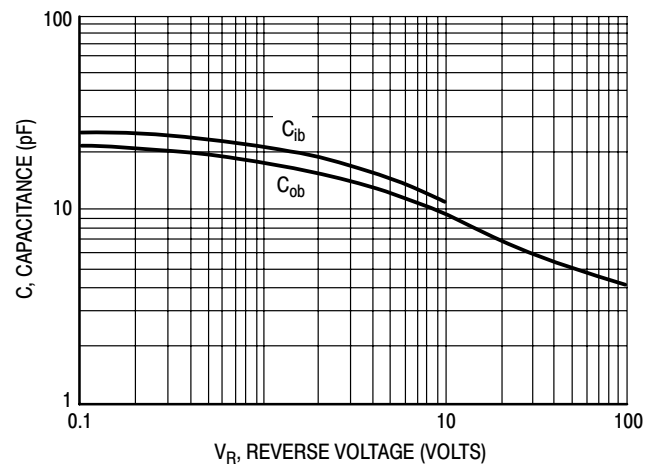
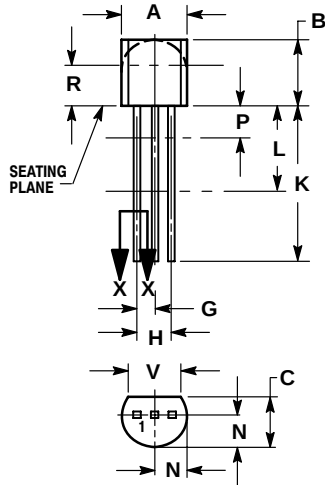


Figure 4. Capacitances

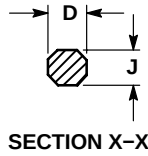
BC372, BC373

PACKAGE DIMENSIONS

TO-92 (TO-226)
CASE 29-11
ISSUE AM



STRAIGHT LEAD
BULK PACK

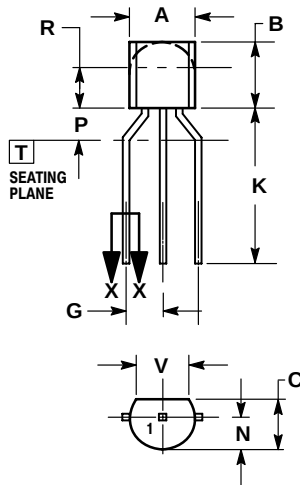


SECTION X-X

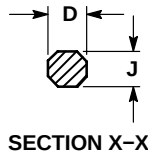
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD
TAPE & REEL
AMMO PACK



SECTION X-X

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 1:

1. PIN 1. EMITTER
2. BASE
3. COLLECTOR

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